PCN # 1708B

DATE: March 13, 2019

EXPECTED PCN SHIP DATE: March 13, 2019

Quality Assurance
160 Rio Robles
San Jose, CA 95134

www.maximintegrated.com

☐ PROCESS CHANGE NOTICE
☒ PRODUCT CHANGE NOTICE

MAXIM INTEGRATED HEREBY ISSUES NOTIFICATION OF CHANGE
THAT MAY AFFECT THE FOLLOWING CATEGORIES:

☐ DESIGN	☐ WAFER FAB	☒ ASSEMBLY	☐ TEST	☐ ELEC/MECH SPECS

AFFECTED PRODUCT:

Ordering P/N: (See PN listing XLS in PCN ZIP file)

CHANGE FROM: Assembler Carsem, Automotive grade products in SOT23/SC70 1. Conductive die attach adhesive ABLEBOND 84-1LMISR4 2. Mold compound CEL9220HF13 (for MAX6070, CEL8240HF10-LXC)	CHANGE TO: - 1. Conductive Die Attach Film CDAF815 (applied at assembly manufacturing) 2. Mold compound G700LS

JUSTIFICATION: -

1. Changing the process to replace the use of adhesive die attach with Conductive Die Attach Film (CDAF) will improve device quality/reliability by eliminating the risk of a short between die paddle and lead due to the possibility of an excessive adhesive drop-on.
2. To align with Maxim other subcontractors that are using the same compound, with same standard of quality in automotive products.

Qualification results are provided in attached report (R29165FQ_Carsem_Rev2).

There is no impact to the form/fit/function of the devices.

TRACEABILITY: Maxim Integrated maintains full traceability by device marking, packaging labels and shipment documents.

Maxim Integrated's Change Notification System is designed to keep our customer base apprised of major product, manufacturing, or facility improvements.

Nasser Ali Chaouche

Nasser AliChaouche / PCN Coordinator

For further information, please contact either of the people listed below.

Contact your local Maxim Integrated Company Representative or Nasser AliChaouche, PCN Coordinator
408-601-5660 / pcn.coordinator@maximintegrated.com